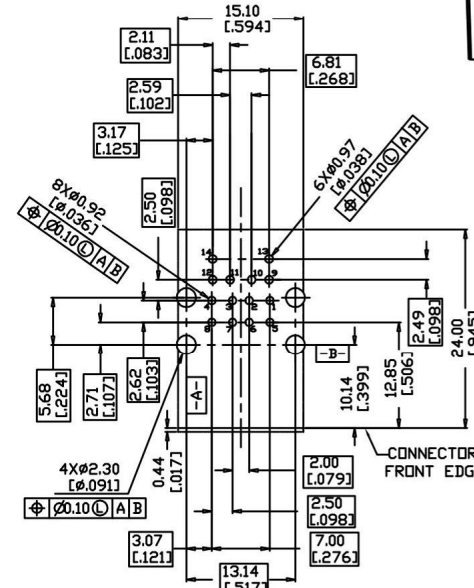
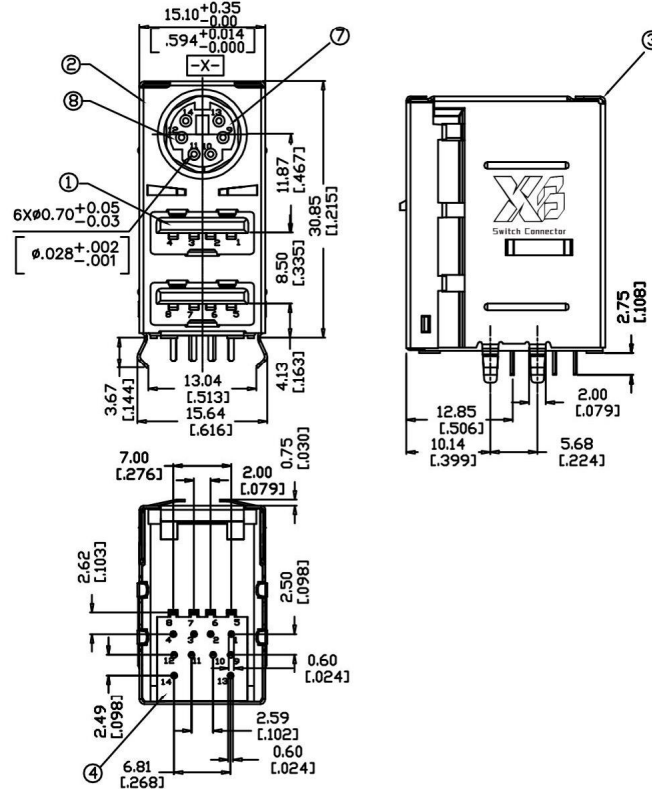
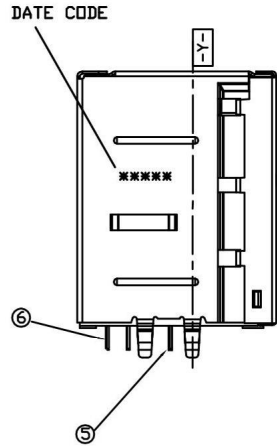
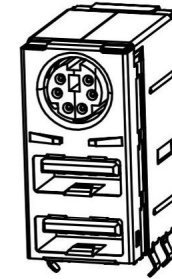


REV.	ECN. NO.	APPD.
X1	5/13'08	Hao Gu
X2	5/21'08	Hao Gu
X3	10/7'08	Hao Gu
X4	1/7'10	Adward Zheng
X5	2/4'10	Adward Zheng



PCB LAYOUT (COMPONENT SIDE VIEW)
PCB T=1.57mm, DEFAULT TOL. ±0.05[.002]

- NOTES:
- USB SPECIFICATION
 - ELECTRICAL CHARACTERISTICS:
 - CONTACT CURRENT RATING: 1.5 AMPERE.
 - CONTACT RESISTANCE: 30 MILLIOHMS MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500 VAC MIN. ONE MINUTE.
 - INSULATION RESISTANCE: 1000 MEGOHMS MIN.
 - MECHANICAL CHARACTERISTICS:
 - CONNECTOR MATING FORCE: 3.5 Kgf MAX.
 - CONNECTOR UNMATING FORCE: 1.0 Kgf MIN.
 - DURABILITY: AFTER 1500 CYCLES MEET USB 2.0 SPEC. AFTER 6000 CYCLES, CONTACT RESISTANCE CHANGE FROM INITIAL VALUE: 30 MILLIOHMS MAX.
 - OPERATING TEMPERATURE: -55°C TO +85°C
 - MINI DIN SPECIFICATION
 - ELECTRICAL CHARACTERISTICS:
 - CONNECTOR RATED CURRENT: 2A RATED VOLTAGE: 12V
 - INSULATION RESISTANCE: 30 MEGOHMS MINIMUM UNDER THE TEST CONDITION OF 100VDC APPLIED BETWEEN TWO INSULATED PARTS
 - DIELECTRIC WITHSTANDING VOLTAGE: 500 VAC, FOR ONE MINUTE
 - CONTACT RESISTANCE: 30 MILLIOHMS MAXIMUM
 - MECHANICAL CHARACTERISTICS:
 - MATING FORCE: 45N(4.5Kgf) MAX. UNMATING FORCE: 3N(0.3Kgf) MIN.
 - DURABILITY: 500 CYCLES.
 - TEMPERATURE RANGE: -25~70°C
 - RECOMMENDED PROCESS AND TEMPERATURE: WAVE SOLDER 260°C, 3-5 SECONDS.
 - PRODUCT IS ROHS COMPLIANT.

ITEM	DESCRIPTION	Q'TY	MATERIAL	FINISH
8	MINIDIN HOUSING LEFT	1	THERMOPLASTIC; UL 94V-0	MOLDED PURPLE
7	MINIDIN HOUSING RIGHT	1	THERMOPLASTIC; UL 94V-0	MOLDED GREEN
6	MINIDIN CONTACT	6	COPPER ALLOY	NICKEL UNDERPLATED OVER ALL. GOLD PLATED (30u"MIN) AT CONTACT AREA LEAD FREE TIN ALLOY AT TERMINATION, UB11123-HFD2-4F
				NICKEL UNDERPLATED OVER ALL. GOLD PLATED (1~3u") AT CONTACT AREA LEAD FREE TIN ALLOY AT TERMINATION, UB11121-HFD2-4F
5	USB CONTACT	8	COPPER ALLOY	NICKEL UNDERPLATED OVER ALL. GOLD PLATED (30u"MIN) AT CONTACT AREA LEAD FREE TIN ALLOY AT TERMINATION, UB11123-HFD2-4F
				NICKEL UNDERPLATED OVER ALL. GOLD PLATED (1~3u") AT CONTACT AREA LEAD FREE TIN ALLOY AT TERMINATION, UB11121-HFD2-4F
4	SPACER	1	THERMOPLASTIC; UL 94V-0	MOLDED BLACK
3	REAR SHELL	1	IRON ALLOY	NICKEL PLATED OVER ALL
2	FRONT SHELL	1	STAINLESS STEEL	CLEAN
1	USB HOUSING	1	THERMOPLASTIC; UL 94V-0	MOLDED BLACK

X. ±	X*. ±	UNITS	NAME (INTENDED USE)	东莞市溪榜电子有限公司 DONG GUAN XI BANG ELECTRONICS CO., LTD.
.X ± 0.3 [0.12]	.X* ±	MAT'L	CUSTOMER	
.XX ± 0.25 [0.10]	.XX* ±	N/A	PART NO. (INTENDED USE)	TITLE:
.XXX ±	.XXX* ±	FINISH	UB112*-HFD2-4F	STACKED USB MINIDIN COMBO
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			CHKD: Jesse Wang 2/4'10	SCALE SHEET REV. N/A 1/1 X5
			DR: S.Y. Li 2/4'10	